


ISSN 1726-5479

SENSORS & TRANSDUCERS

8^{vol. 143}
/12



Sensors and Transducers Applications

International Frequency Sensor Association Publishing



Editors-in-Chief: professor Sergey Y. Yurish, tel.: +34 696067716, e-mail: editor@sensorsportal.com**Editors for Western Europe**Meijer, Gerard C.M., Delft University of Technology, The Netherlands
Ferrari, Vittorio, Università di Brescia, Italy**Editors for North America**Datskos, Panos G., Oak Ridge National Laboratory, USA
Fabien, J. Josse, Marquette University, USA
Katz, Evgeny, Clarkson University, USA**Editor South America**

Costa-Felix, Rodrigo, Inmetro, Brazil

Editor for Eastern Europe

Sachenko, Anatoly, Ternopil State Economic University, Ukraine

Editor for Asia

Ohyama, Shinji, Tokyo Institute of Technology, Japan

Editor for Africa

Maki K.Habib, American University in Cairo, Egypt

Editor for Asia-Pacific

Mukhopadhyay, Subhas, Massey University, New Zealand

Editorial Advisory Board

- Abdul Rahim, Ruzairi**, Universiti Teknologi, Malaysia
Ahmad, Mohd Noor, Northern University of Engineering, Malaysia
Annamalai, Karthigeyan, National Institute of Advanced Industrial Science and Technology, Japan
Arcega, Francisco, University of Zaragoza, Spain
Arguel, Philippe, CNRS, France
Ahn, Jae-Pyoung, Korea Institute of Science and Technology, Korea
Arndt, Michael, Robert Bosch GmbH, Germany
Ascoli, Giorgio, George Mason University, USA
Atalay, Selcuk, Inonu University, Turkey
Atghiaee, Ahmad, University of Tehran, Iran
Augutis, Vygtantas, Kaunas University of Technology, Lithuania
Avachit, Patil Lalchand, North Maharashtra University, India
Ayesh, Aladdin, De Montfort University, UK
Azamimi, Azian binti Abdullah, Universiti Malaysia Perlis, Malaysia
Bahreyni, Behraad, University of Manitoba, Canada
Baliga, Shankar, B., General Motors Transnational, USA
Baoxian, Ye, Zhengzhou University, China
Barford, Lee, Agilent Laboratories, USA
Barlingay, Ravindra, RF Arrays Systems, India
Basu, Sukumar, Jadavpur University, India
Beck, Stephen, University of Sheffield, UK
Ben Bouzid, Sihem, Institut National de Recherche Scientifique, Tunisia
Benachaiba, Chellali, Universitè de Bechar, Algeria
Binnie, T. David, Napier University, UK
Bischoff, Gerlinde, Inst. Analytical Chemistry, Germany
Bodas, Dhananjay, IMTEK, Germany
Borges Carval, Nuno, Universidade de Aveiro, Portugal
Bouchikhi, Benachir, University Moulay Ismail, Morocco
Bousbia-Salah, Mounir, University of Annaba, Algeria
Bouvet, Marcel, CNRS – UPMC, France
Brudzewski, Kazimierz, Warsaw University of Technology, Poland
Cai, Chenxin, Nanjing Normal University, China
Cai, Qingyun, Hunan University, China
Calvo-Gallego, Jaime, Universidad de Salamanca, Spain
Campanella, Luigi, University La Sapienza, Italy
Carvalho, Vitor, Minho University, Portugal
Cecelja, Franjo, Brunel University, London, UK
Cerda Belmonte, Judith, Imperial College London, UK
Chakrabarty, Chandan Kumar, Universiti Tenaga Nasional, Malaysia
Chakravorty, Dipankar, Association for the Cultivation of Science, India
Changhai, Ru, Harbin Engineering University, China
Chaudhari, Gajanan, Shri Shivaji Science College, India
Chavali, Murthy, N.I. Center for Higher Education, (N.I. University), India
Chen, Jiming, Zhejiang University, China
Chen, Rongshun, National Tsing Hua University, Taiwan
Cheng, Kuo-Sheng, National Cheng Kung University, Taiwan
Chiang, Jeffrey (Cheng-Ta), Industrial Technol. Research Institute, Taiwan
Chiriac, Horia, National Institute of Research and Development, Romania
Chowdhuri, Arijit, University of Delhi, India
Chung, Wen-Yaw, Chung Yuan Christian University, Taiwan
Corres, Jesus, Universidad Publica de Navarra, Spain
Cortes, Camilo A., Universidad Nacional de Colombia, Colombia
Courtois, Christian, Universite de Valenciennes, France
Cusano, Andrea, University of Sannio, Italy
D'Amico, Arnaldo, Università di Tor Vergata, Italy
De Stefano, Luca, Institute for Microelectronics and Microsystem, Italy
Deshmukh, Kiran, Shri Shivaji Mahavidyalaya, Barshi, India
Dickert, Franz L., Vienna University, Austria
Dieguez, Angel, University of Barcelona, Spain
Dighavkar, C. G., M.G. Vidyamandir's L. V.H. College, India
Dimitropoulos, Panos, University of Thessaly, Greece
Ding, Jianning, Jiangsu Polytechnic University, China
Djordjevic, Alexander, City University of Hong Kong, Hong Kong
Donato, Nicola, University of Messina, Italy
Donato, Patricio, Universidad de Mar del Plata, Argentina
Dong, Feng, Tianjin University, China
Drljaca, Predrag, Instersema Sensoric SA, Switzerland
Dubey, Venketesh, Bournemouth University, UK
Enderle, Stefan, Univ. of Ulm and KTB Mechatronics GmbH, Germany
Erdem, Gursan K. Arzum, Ege University, Turkey
Erkmen, Aydan M., Middle East Technical University, Turkey
Estelle, Patrice, Insa Rennes, France
Estrada, Horacio, University of North Carolina, USA
Faiz, Adil, INSA Lyon, France
Fericean, Sorin, Balluff GmbH, Germany
Fernandes, Joana M., University of Porto, Portugal
Francioso, Luca, CNR-IMM Institute for Microelectronics and Microsystems, Italy
Francis, Laurent, University Catholique de Louvain, Belgium
Fu, Weiling, South-Western Hospital, Chongqing, China
Gaura, Elena, Coventry University, UK
Geng, Yanfeng, China University of Petroleum, China
Gole, James, Georgia Institute of Technology, USA
Gong, Hao, National University of Singapore, Singapore
Gonzalez de la Rosa, Juan Jose, University of Cadiz, Spain
Granell, Annette, Goteborg University, Sweden
Graff, Mason, The University of Texas at Arlington, USA
Guan, Shan, Eastman Kodak, USA
Guillet, Bruno, University of Caen, France
Guo, Zhen, New Jersey Institute of Technology, USA
Gupta, Narendra Kumar, Napier University, UK
Hadjiloucas, Sillas, The University of Reading, UK
Haider, Mohammad R., Sonoma State University, USA
Hashsham, Syed, Michigan State University, USA
Hasni, Abdelhafid, Bechar University, Algeria
Hernandez, Alvaro, University of Alcalá, Spain
Hernandez, Wilmar, Universidad Politecnica de Madrid, Spain
Homentcovschi, Dorel, SUNY Binghamton, USA
Horstman, Tom, U.S. Automation Group, LLC, USA
Hsiai, Tzung (John), University of Southern California, USA
Huang, Jeng-Sheng, Chung Yuan Christian University, Taiwan
Huang, Star, National Tsing Hua University, Taiwan
Huang, Wei, PSG Design Center, USA
Hui, David, University of New Orleans, USA
Jaffrezic-Renault, Nicole, Ecole Centrale de Lyon, France
James, Daniel, Griffith University, Australia
Janting, Jakob, DELTA Danish Electronics, Denmark
Jiang, Liudi, University of Southampton, UK
Jiang, Wei, University of Virginia, USA
Jiao, Zheng, Shanghai University, China
John, Joachim, IMEC, Belgium
Kalach, Andrew, Voronezh Institute of Ministry of Interior, Russia
Kang, Moonho, Sunmoon University, Korea South
Kaniasas, Eugenijus, Vienna University of Technology, Austria
Katake, Anup, Texas A&M University, USA
Kausel, Wilfried, University of Music, Vienna, Austria
Kavasoglu, Nese, Mugla University, Turkey
Ke, Cathy, Tyndall National Institute, Ireland
Khelfaoui, Rachid, Université de Bechar, Algeria
Khan, Asif, Aligarh Muslim University, Aligarh, India
Kim, Min Young, Kyungpook National University, Korea South
Ko, Sang Choon, Electronics. and Telecom. Research Inst., Korea South
Kotulska, Malgorzata, Wroclaw University of Technology, Poland
Kockar, Hakan, Balikesir University, Turkey
Kong, Ing, RMIT University, Australia
Kratz, Henrik, Uppsala University, Sweden

Krishnamoorthy, Ganesh, University of Texas at Austin, USA
Kumar, Arun, University of Delaware, Newark, USA
Kumar, Subodh, National Physical Laboratory, India
Kung, Chih-Hsien, Chang-Jung Christian University, Taiwan
Lacnjevac, Caslav, University of Belgrade, Serbia
Lay-Ekuakille, Aime, University of Lecce, Italy
Lee, Jang Myung, Pusan National University, Korea South
Lee, Jun Su, Amkor Technology, Inc. South Korea
Lei, Hua, National Starch and Chemical Company, USA
Li, Fengyuan (Thomas), Purdue University, USA
Li, Genxi, Nanjing University, China
Li, Hui, Shanghai Jiaotong University, China
Li, Sihua, Agiltron, Inc., USA
Li, Xian-Fang, Central South University, China
Li, Yuefa, Wayne State University, USA
Liang, Yuanchang, University of Washington, USA
Liawruangrath, Saisunee, Chiang Mai University, Thailand
Liew, Kim Meow, City University of Hong Kong, Hong Kong
Lin, Hermann, National Kaohsiung University, Taiwan
Lin, Paul, Cleveland State University, USA
Linderholm, Pontus, EPFL - Microsystems Laboratory, Switzerland
Liu, Aihua, University of Oklahoma, USA
Liu Changgeng, Louisiana State University, USA
Liu, Cheng-Hsien, National Tsing Hua University, Taiwan
Liu, Songqin, Southeast University, China
Lodeiro, Carlos, University of Vigo, Spain
Lorenzo, Maria Encarnacio, Universidad Autonoma de Madrid, Spain
Lukaszewicz, Jerzy Pawel, Nicholas Copernicus University, Poland
Ma, Zhanfang, Northeast Normal University, China
Majstorovic, Vidosav, University of Belgrade, Serbia
Malyshev, V.V., National Research Centre 'Kurchatov Institute', Russia
Marquez, Alfredo, Centro de Investigacion en Materiales Avanzados, Mexico
Matay, Ladislav, Slovak Academy of Sciences, Slovakia
Mathur, Prafull, National Physical Laboratory, India
Maurya, D.K., Institute of Materials Research and Engineering, Singapore
Mekid, Samir, University of Manchester, UK
Melnyk, Ivan, Photon Control Inc., Canada
Mendes, Paulo, University of Minho, Portugal
Mennell, Julie, Northumbria University, UK
Mi, Bin, Boston Scientific Corporation, USA
Minas, Graca, University of Minho, Portugal
Mishra, Vivekanand, National Institute of Technology, India
Moghavvemi, Mahmoud, University of Malaya, Malaysia
Mohammadi, Mohammad-Reza, University of Cambridge, UK
Molina Flores, Esteban, Benemérita Universidad Autónoma de Puebla, Mexico
Moradi, Majid, University of Kerman, Iran
Morello, Rosario, University "Mediterranea" of Reggio Calabria, Italy
Mounir, Ben Ali, University of Sousse, Tunisia
Mrad, Nezh, Defence R&D, Canada
Mulla, Imtiaz Sirajuddin, National Chemical Laboratory, Pune, India
Nabok, Aleksey, Sheffield Hallam University, UK
Neelamegam, Periasamy, Sastra Deemed University, India
Neshkova, Milka, Bulgarian Academy of Sciences, Bulgaria
Oberhammer, Joachim, Royal Institute of Technology, Sweden
Ould Lahoucine, Cherif, University of Guelma, Algeria
Pamidighanta, Sayanu, Bharat Electronics Limited (BEL), India
Pan, Jisheng, Institute of Materials Research & Engineering, Singapore
Park, Joon-Shik, Korea Electronics Technology Institute, Korea South
Passaro, Vittorio M. N., Politecnico di Bari, Italy
Penza, Michele, ENEA C.R., Italy
Pereira, Jose Miguel, Instituto Politecnico de Seteбал, Portugal
Petsev, Dimiter, University of New Mexico, USA
Pogacnik, Lea, University of Ljubljana, Slovenia
Post, Michael, National Research Council, Canada
Prance, Robert, University of Sussex, UK
Prasad, Ambika, Gulbarga University, India
Prateepasen, Asa, Kingmoungut's University of Technology, Thailand
Pugno, Nicola M., Politecnico di Torino, Italy
Pullini, Daniele, Centro Ricerche FIAT, Italy
Pumera, Martin, National Institute for Materials Science, Japan
Radhakrishnan, S., National Chemical Laboratory, Pune, India
Rajanna, K., Indian Institute of Science, India
Ramadan, Qasem, Institute of Microelectronics, Singapore
Rao, Basuthkar, Tata Inst. of Fundamental Research, India
Raouf, Kosai, Joseph Fourier University of Grenoble, France
Rastogi Shiva, K., University of Idaho, USA
Reig, Candid, University of Valencia, Spain
Restivo, Maria Teresa, University of Porto, Portugal
Robert, Michel, University Henri Poincare, France
Rezazadeh, Ghader, Urmia University, Iran
Royo, Santiago, Universitat Politècnica de Catalunya, Spain
Rodriguez, Angel, Universitat Politècnica de Catalunya, Spain
Rothberg, Steve, Loughborough University, UK
Sadana, Ajit, University of Mississippi, USA
Sadeghian Marnani, Hamed, TU Delft, The Netherlands
Sapozhnikova, Ksenia, D.I.Mendeleyev Institute for Metrology, Russia
Sandacci, Serghei, Sensor Technology Ltd., UK
Saxena, Vibha, Bbhba Atomic Research Centre, Mumbai, India
Schneider, John K., Ultra-Scan Corporation, USA
Sengupta, Deepak, Advance Bio-Photonics, India
Seif, Selemani, Alabama A & M University, USA
Seifter, Achim, Los Alamos National Laboratory, USA
Shah, Kriyang, La Trobe University, Australia
Sankarraaj, Anand, Detector Electronics Corp., USA
Silva Giroa, Pedro, Technical University of Lisbon, Portugal
Singh, V. R., National Physical Laboratory, India
Slomovitz, Daniel, UTE, Uruguay
Smith, Martin, Open University, UK
Soleimanpour, Amir Masoud, University of Toledo, USA
Soleymanpour, Ahmad, University of Toledo, USA
Somani, Prakash R., Centre for Materials for Electronics Technol., India
Sridharan, M., Sastra University, India
Srinivas, Talabattula, Indian Institute of Science, Bangalore, India
Srivastava, Arvind K., NanoSonix Inc., USA
Stefan-van Staden, Raluca-Ioana, University of Pretoria, South Africa
Stefanescu, Dan Mihai, Romanian Measurement Society, Romania
Sumriddetchka, Sarun, National Electronics and Comp. Technol. Center, Thailand
Sun, Chengliang, Polytechnic University, Hong-Kong
Sun, Dongming, Jilin University, China
Sun, Junhua, Beijing University of Aeronautics and Astronautics, China
Sun, Zhiqiang, Central South University, China
Suri, C. Raman, Institute of Microbial Technology, India
Sysoev, Victor, Saratov State Technical University, Russia
Szewczyk, Roman, Industr. Research Inst. for Automation and Measurement, Poland
Tan, Ooi Kiang, Nanyang Technological University, Singapore
Tang, Dianping, Southwest University, China
Tang, Jaw-Luen, National Chung Cheng University, Taiwan
Teker, Kasif, Frostburg State University, USA
Thirunavukkarasu, I., Manipal University Karnataka, India
Thumbavanam Pad, Kartik, Carnegie Mellon University, USA
Tian, Gui Yun, University of Newcastle, UK
Tsiantos, Vassilios, Technological Educational Institute of Kaval, Greece
Tsigara, Anna, National Hellenic Research Foundation, Greece
Twomey, Karen, University College Cork, Ireland
Valente, Antonio, University, Vila Real, - U.T.A.D., Portugal
Vanga, Raghav Rao, Summit Technology Services, Inc., USA
Vaseashta, Ashok, Marshall University, USA
Vazquez, Carmen, Carlos III University in Madrid, Spain
Vieira, Manuela, Instituto Superior de Engenharia de Lisboa, Portugal
Vigna, Benedetto, STMicroelectronics, Italy
Vrba, Radimir, Brno University of Technology, Czech Republic
Wandelt, Barbara, Technical University of Lodz, Poland
Wang, Jiangping, Xi'an Shiyou University, China
Wang, Kedong, Beihang University, China
Wang, Liang, Pacific Northwest National Laboratory, USA
Wang, Mi, University of Leeds, UK
Wang, Shinn-Fwu, Ching Yun University, Taiwan
Wang, Wei-Chih, University of Washington, USA
Wang, Wensheng, University of Pennsylvania, USA
Watson, Steven, Center for NanoSpace Technologies Inc., USA
Weiping, Yan, Dalian University of Technology, China
Wells, Stephen, Southern Company Services, USA
Wolkenberg, Andrzej, Institute of Electron Technology, Poland
Woods, R. Clive, Louisiana State University, USA
Wu, DerHo, National Pingtung Univ. of Science and Technology, Taiwan
Wu, Zhaoyang, Hunan University, China
Xiu Tao, Ge, Chuzhou University, China
Xu, Lisheng, The Chinese University of Hong Kong, Hong Kong
Xu, Sen, Drexel University, USA
Xu, Tao, University of California, Irvine, USA
Yang, Dongfang, National Research Council, Canada
Yang, Shuang-Hua, Loughborough University, UK
Yang, Wuqiang, The University of Manchester, UK
Yang, Xiaoling, University of Georgia, Athens, GA, USA
Yaping Dan, Harvard University, USA
Ymeti, Aurel, University of Twente, Netherland
Yong Zhao, Northeastern University, China
Yu, Haihu, Wuhan University of Technology, China
Yuan, Yong, Massey University, New Zealand
Yufera Garcia, Alberto, Seville University, Spain
Zakaria, Zulkarnay, University Malaysia Perlis, Malaysia
Zagnoni, Michele, University of Southampton, UK
Zamani, Cyrus, Universitat de Barcelona, Spain
Zeni, Luigi, Second University of Naples, Italy
Zhang, Minglong, Shanghai University, China
Zhang, Qintao, University of California at Berkeley, USA
Zhang, Weiping, Shanghai Jiao Tong University, China
Zhang, Wenming, Shanghai Jiao Tong University, China
Zhang, Xueji, World Precision Instruments, Inc., USA
Zhong, Haoxiang, Henan Normal University, China
Zhu, Qing, Fujifilm Dimatix, Inc., USA
Zorzano, Luis, Universidad de La Rioja, Spain
Zourob, Mohammed, University of Cambridge, UK

Contents

Volume 143
Issue 8
August 2012

www.sensorsportal.com


ISSN 1726-5479

Research Articles

Research in Nanothermometry. Part 7. Ultrasonic Thermometer Based on Nanostructured Thermometric Substance , Bohdan Stadnyk, Svyatoslav Yatsyshyn, Yaroslav Lutsyk, Pylyp Skoropad, Zenoviy Kolodiy, Orysyia Kozak	1
Plasma Polymerized Thin Film Sensor: Synthesis and Application K. A. Koparkar	10
Current Trend of Tactile Sensor in Advanced Applications Ruzairi Abdul Rahim , Mohamed Faisal Abdul Waduth, Haziq Izzuan Jaafar, Nor Muzakkir Nor Ayob, Pei Ling Leow.....	32
Quartz Crystal Microbalance DNA Based Biosensor for Diagnosis: A Review Thongchai Kaewphinit, Somchai Santiwatanakul, and Kosum Chansiri.....	44
Review on Interaction between Electromagnetic Field and Biological Tissues Zulkarnay Zakaria, Abdul Rahim, Pick Yern Lee, Muhammad Saiful Badri Mansor, Azian Azamimi Abdullah, Sazali Yaacob, Siti Zarina Mohd. Muji.....	60
Force Measurement Using Magnetic Potentiometer Sunan Huang, Haoyong Yu.....	71
A New Method for Linear Compression and Decompression of Sequential Sensor Signals Zhiqiang Sun, Zhiyong Li.....	79
FPGA-Based Temperature Monitoring and Control System for Infant Incubator Bharathi Navaneethkrishnan, Neelamegam P.	88
Design and Simulation of a Novel MEMS Based Linear Actuator for Mirror Shape Correction Applications , Ehsan Atashzaban.....	98
Virtual Prototyping of a MEMS Capacitive Pressure Sensor for Tire Pressure Monitoring System Using Intellisuite , Anurekha Sharma, Munju Mittal, Deepika Saini.....	106
Low Cost of Preparation of Infrared PbS Detector Using Copper Electrodes of PCB Hariyadi Soetedjo, Gunawan S. Prabowo and Darsono	120
System Identification of MOS Gas Sensors and Stability Analysis Nimisha Dutta, Sumi Kankana Dewan and Manabendra Bhuyan.....	127
Tin Modified Tungsten Oxide Thin Film for Ammonia Gas Sensing at Room Temperature K. J. Patel, M. S. Desai, C. J. Panchal.	136
Electrochemical Based Diagnosis of Ascorbic Acid Anjum Gahlaut, Ashish Gothwal, Anil K. Chhillar, Vikas Hooda	143
Resistive Type Moisture Sensor Based on WO₃ Nanomaterial Anupam Tripathi, Karunesh Tiwari, N. K. Pandey, Vidhu Tripathi	152

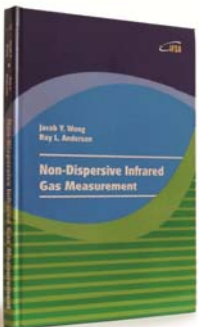
Authors are encouraged to submit article in MS Word (doc) and Acrobat (pdf) formats by e-mail: editor@sensorsportal.com
Please visit journal's webpage with preparation instructions: <http://www.sensorsportal.com/HTML/DIGEST/Submission.htm>

International Frequency Sensor Association (IFSA).

 **International Frequency Sensor Association (IFSA) Publishing**

NEW BOOK

Jacob Y. Wong, Roy L. Anderson
Non-Dispersive Infrared Gas Measurement




Written by experts in the field, the *Non-Dispersive Infrared Gas Measurement* begins with a brief survey of various gas measurement techniques and continues with fundamental aspects and cutting-edge progress in NDIR gas sensors in their historical development.

- It addresses various fields, including:
- Interactive and non-interactive gas sensors
- Non-dispersive infrared gas sensors' components
- Single- and Double beam designs
- Historical background and today's of NDIR gas measurements

Providing sufficient background information and details, the book *Non-Dispersive Infrared Gas Measurement* is an excellent resource for advanced level undergraduate and graduate students as well as researchers, instrumentation engineers, applied physicists, chemists, material scientists in gas, chemical, biological, and medical sensors to have a comprehensive understanding of the development of non-dispersive infrared gas sensors and the trends for the future investigation.

Formats: printable pdf (Acrobat) and print (hardcover), 120 pages
ISBN: 978-84-615-9732-1,
e-ISBN: 978-84-615-9512-9

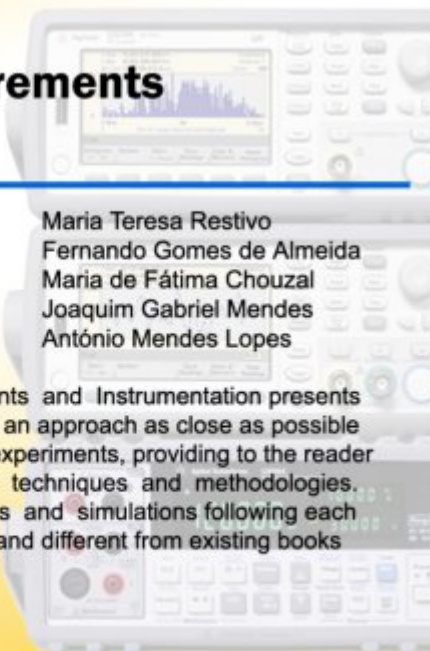
http://sensorsportal.com/HTML/BOOKSTORE/NDIR_Gas_Measurement.htm



Handbook of Laboratory Measurements and Instrumentation

**Maria Teresa Restivo
Fernando Gomes de Almeida
Maria de Fátima Chouzal
Joaquim Gabriel Mendes
António Mendes Lopes**

The Handbook of Laboratory Measurements and Instrumentation presents experimental and laboratory activities with an approach as close as possible to reality, even offering remote access to experiments, providing to the reader an excellent tool for learning laboratory techniques and methodologies. Book includes dozens videos, animations and simulations following each of chapters. It makes the title very valued and different from existing books on measurements and instrumentation.

 **International Frequency Sensor Association Publishing**

Order online:
http://www.sensorsportal.com/HTML/BOOKSTORE/Handbook_of_Measurements.htm

Current Trend of Tactile Sensor in Advanced Applications

**Ruzairi ABDUL RAHIM , Mohamed Faisal ABDUL WADUTH,
Haziq Izzuan JAAFAR, Nor Muzakkir NOR AYOB, Pei Ling LEOW**
Process Tomography Research Group (PROTOM), Faculty of Electrical Engineering,
Universiti Teknologi Malaysia,
81310 Skudai, Johor Bahru, Johor, Malaysia
E-mail: ruzairi@fke.utm.my

Received: 22 May 2012 /Accepted: 21 August 2012 /Published: 28 August 2012

Abstract: Tactile sensor is one of the important tactile technologies which discovered in the 1980s. It grows in line with development of robotics and computers. From current development trends, varieties of application areas from tactile sensor have been proposed. In this paper, developments of tactile sensor have been reviewed and the applications from previous five years journals are discussed. The transduction techniques, their relative advantages and disadvantages, latest application area of tactile sensor and contribution are analyzed. *Copyright © 2012 IFSA.*

Keywords: Tactile sensor, Tissue elasticity, Human-interactive robot, Polydimethylsiloxane (PDMS), Capacitive sensor, Ionic polymer metal composite (IPMC), Fabric tactile sensor.

1. Introduction

Today, we realized that vision, taste, touch, smell and sound sensory receptors are very important. Interaction with environment would make more meaningful in daily life. If one of sense not functions, human will not feel pleasure life such as before. Due to this, tactile sensor is created and develops to overcome and applied in the real life application.

Although tactile sensor was not a main research field compared the other sensor, the use of tactile sensor in products to improve quality of human life especially in the field of biomedical, robotic, and medical [1].

Early researchers, such as Harmon sees robotics fields have a good potential and future application of tactile sensing. Due to technical difficulties and low return investment, Harmon experience tactile sensing is not suitable for medicine and agriculture fields. Furthermore, other researchers such as Whitney and Nevins argued that passive monitoring will eliminate the need of tactile sensing.

Beginning of 21st century, it was predicted that this tactile technology would have the potential to sustain the growth of more intellectual system and product. In directly, it would develop the quality of human life [2]. However, tactile technology unsuccessful to expand and achieved the target market in 1990s. Unawares, tactile technology gradually grow and known time by time with many researcher. Now, it is not only useful in robotics area but it also has been involved in medical and biomedical engineering.

Four papers have been selected from the past five years journals to review their development to the variety of applications in medical field [3], robotics fields [4], image processing fields [5, 6] and biomedical field [7-10]. Details of the discussion will highlighted in part III, IV, and V.

2. Theory

2.1. What is Tactile Sensor

The term of tactile sensor is refers to the transducer that is sensitive to touch, force and pressure [1]. It is devices which receives and give feedback or respond to a signal having to do with force. Furthermore, it is required tactile information through physical touch. The temperature, vibration, softness, texture, shape, composition and shear and normal forces are the properties of measured parameter for tactile sensor. One or more of these properties can be measured by tactile sensor. Even though pressure and torque sensing is often not included in the definition of tactile sensing, pressure and torque are also important properties, typically acquired by physical touch, and can be included as tactile parameters.

2.2. Tactile Transduction Techniques

Normally, tactile transduction techniques are based on capacitive, piezoresistive, piezoelectric, and optoelectric methods. All of these techniques have their own advantages and disadvantages. Usually, capacitive, piezoresistive, piezoelectric, and optoelectric methods give a better performance and effectiveness. It always becomes a best choice to many sensor designers in order to develop the tactile application. In this section, all of these methods and their relative advantages and disadvantages will be discussed. These are also has been summarized in Table I [1].

2.2.1. Capacitive Tactile Sensors

A capacitive sensor contain of two conductive plates with a dielectric material between them [1]. The capacitance can be expressed as, $C = (A\epsilon_0r)/d$ for parallel plate capacitors which is C is the capacitance, A is the overlapping area of the two plates, ϵ_0 is the permittivity of free space, r is the relative permittivity of the dielectric material and d is distance between the plates. Generally, capacitive tactile sensors show a good frequency response, high spatial resolution, and have a large dynamic range. Furthermore, these sensors are more liable to noise, especially in mesh configurations. It is due to crosstalk noise, field connections and fringing capacitance and also requires relatively complex electronics to filter out this noise.

2.2.2. Piezoresistive Tactile Sensors

A pressure sensitive element is included for this sensor. It changes its resistance upon application of force. Simple resistive element can be expressed as, $V = IR$ for the voltage-current characteristic which is V is the voltage, I is the current and R is the resistance of the material. Usually some property of the voltage is fixed. Then change in resistance is observed by a change in the current. This resistive element generally takes the form of a conductive rubber, or conductive ink which is pressure sensitive. They commonly need less electronics only. Change in resistance can easily be quantified and it's easier to manufacture and integrate. They are less disposed to noise and therefore work well in mesh configurations as there is no cross talk or field interaction. The hysteresis will give bad impact to resistive tactile sensors and produce a lower frequency response if compared to capacitive tactile sensors.

2.2.3. Piezoelectric Tactile Sensors

A variety of materials such as certain crystals and some ceramics will generate a voltage potential when the crystal lattice is distorted [11]. Its structure may influence the sensitivity of the crystal and allowing it to distinguish between transverse, longitudinal and shear forces. The voltage, V , generated is directly proportional to the applied force, pressure or strain. These sensors give a very good high-frequency response, which makes them an ideal choice for measuring vibrations. However, due to their large internal resistance, they are limited to measuring dynamic forces and are unable to measure static forces. The charge developed decays with a time constant which is determined by the internal impedance and dielectric constant of the piezoelectric film. While doing sensor design, the things that should be considered are the input impedance of the interface electronics. It is because it significantly will affect the response of the device.

2.2.4. Optoelectric Tactile Sensors

Optoelectric sensors use a light source, transduction medium and a photodetector, the latter often in the form of a camera or a photodiode. Usually transduction occurs when changes in the tactile medium modulate the transmission or reflectance intensity, or the spectrum of the source light, as the applied force varies. The advantages of this sensor are they have high spatial resolution, and are not affecting to common lower frequency electromagnetic interference that generated by electrical systems. However, it still has some disadvantages. The disadvantages for this sensor are due to their size and rigidity (Table 1).

In our review, four papers were chosen as below:

- i. Flexible Tactile Sensor for Tissue Elasticity Measurement [3];
- ii. Development of Tactile Sensor System of a Human-Interactive Robot "RI-MAN" [4];
- iii. Large-size Fabric Tactile Sensor for Detecting Contacted Objects [5];
- iv. A Tactile Sensor for Biomedical Application Based on IPMCs [7].

3. Literature Review

For the first paper [3], in the early stages of tactile sensor research, some weaknesses were found due to the material used in construction. For the purpose of measuring the elasticity, some active sensor prototype developed. However because of the active element in the sensor application, several limitations raised. In a study done by Peng Peng et al [3], they come up with new findings in which

they suggested the use of passive tactile sensor. It is chosen because of the ability to measure tissue elasticity and detecting contact force as well as the pressure distribution on the surface of the sensor.

Table 1. Techniques and relative advantages and disadvantages.

Technique	Modulated Parameter	Advantages	Disadvantages
Capacitive	Change in capacitance	<ul style="list-style-type: none"> • Excellent sensitivity • Good spatial resolution • Large dynamic range 	<ul style="list-style-type: none"> • Stray capacitance • Noise susceptible • Complexity of measurement electronics
Piezo-resistive	Changed in resistance	<ul style="list-style-type: none"> • High spartial resolution • High scanning rate in mesh 	<ul style="list-style-type: none"> • Lower repeatability • Hysterisis • Higher power consumption
Piezo-electric	Strain (stress) polarization	<ul style="list-style-type: none"> • High frequency response • High sensitivity • High dynamic range 	<ul style="list-style-type: none"> • Poor spatial resolution • Dynamic sensing only
Opto-electric	Light intensity/spectrum change	<ul style="list-style-type: none"> • Good sensing range • Good reliability • High repeatability 	<ul style="list-style-type: none"> • Bulky in size • Non-confirmable

Sensor fabrication built on polydimethylsiloxane (PDMS) process because it provides a facility to integrate the sensor to medical instruments. PDMS was chosen because the properties of the advantages such as flexibility, ductility, and bio-compatibility. This sensor consists of two sensing elements with different stiffness values.

The sensing elements can be illustrated like a spring as shown in Fig. 1. The sensor is built with two different spring constant, soft spring (k_s) and hard spring (k_h), where one of spring more elastic than the other. This is because, when a force is applied, it will cause a deflection on the spring and k_s suffer more than k_h . The compatibility condition can be derived as shown in:

$$\partial x_1 = \partial x_2 \rightarrow \frac{F_1(k_h + k_\tau)}{k_h k_\tau} = \frac{F_2(k_s + k_\tau)}{k_s k_\tau} \quad (1)$$

The tissue stiffness can then be calculated from:

$$k_\tau = \frac{k_s - k_h \frac{\partial x_h}{\partial x_s}}{\frac{\partial x_h}{\partial x_s} - 1} \quad (2)$$

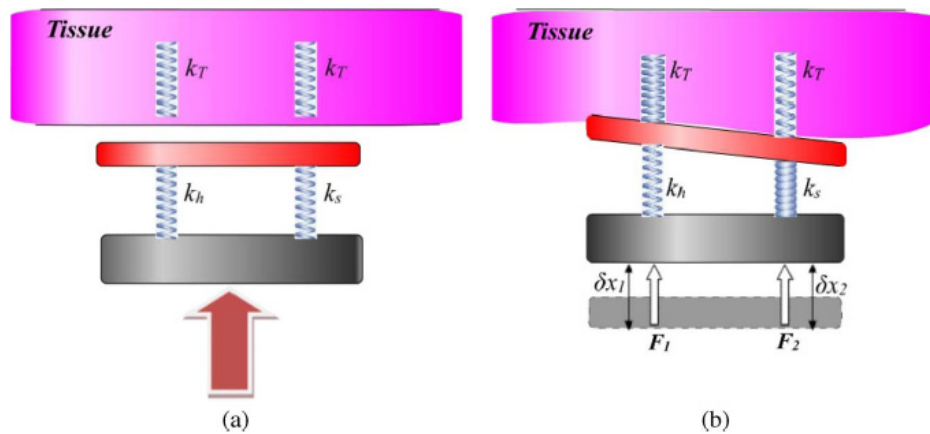


Fig. 1. (a) Schematic diagram of the tactile sensor and the tissue under investigation, (b) Schematic diagram of the contact condition between the tactile sensor and targeted tissue.

From (2), shows the relative deflection of the two sensing elements ($\delta x_h/\delta x_s$) serves as an integral part in calculation tissue stiffness. Capacitive sensing scheme is applied to precisely measure this deflection. To implement the sensing concept, a capacitor pair is designed. Different sizes of sensing membrane are fabricated to vary the stiffness of these diaphragms. The capacitor pair with different sizes is shown in Fig. 2. Each capacitor comprises one top electrode, one bottom electrode, and one single air gap. When the sensor is pushed toward targeted tissue, relative deflection of two sensing membranes can be precisely measured by the capacitive change of each element as shown in Fig. 2(b). This sensor consists of 5 x 5 sensing element and can be attached to any medical instruments built due to thinness of the sensor.

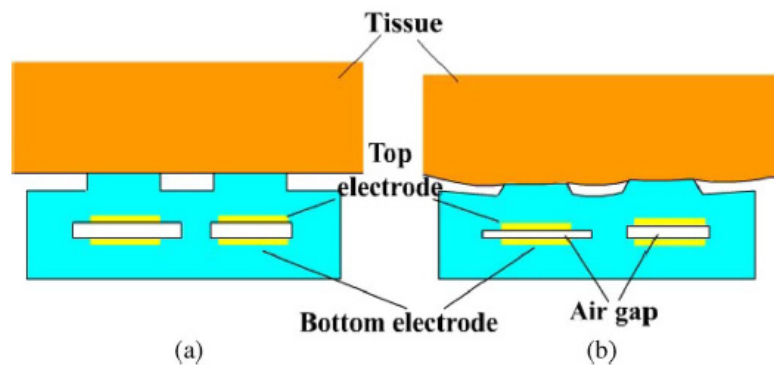


Fig. 2. (a) Conceptual diagram of the proposed flexible tactile sensors under contact with tissue. (b) Different sizes of air gaps of the tactile sensors squeezed by different amounts while pushing toward tissue.

The second paper [4] reflects the usage of tactile sensor for robots. Tactile sensor systems need to be design to implement on the human-interactive robot (RI-MAN). In previous research done by other researcher, sensor developed on the basis of MEMS technologies have high density but narrow covering area. For application of covering large body this will not be suitable. Tactile sensors which have been design for use on robot fingers are mostly able to detect tangential stress and this is good in grasping or force control. Unfortunately, it is suitable only for small area such as finger. The need for tactile sensor for human-interactive robot is need for manipulate objects, interacts and communicate with humans by touch and it should be soft and compatible with curved robot surfaced.

Previously some soft tactile systems for large surface have been developed. It is not suitable, when a physical labor using a tactile sensation is required. Flexible fabric-based tactile sensors using an electrically conductive fabric also propose but since the sensors are binary switches and it is difficult to build. Toshiharu et. al. [4] are currently developing soft areal tactile sensor by embedding semiconductor pressure sensors as pressure sensing elements in an elastic body. This is to provide pressure strength and distribution that can be used to control manipulator.

Few specifications are highlighted for tactile sensor system. First is spatial resolution. This is necessary to realize a resolution similar to that of a human. Second is measurement resolution. This is necessary for the feedback control to be smooth. For tactile sensor controller, some specification also highlighted. First, each controller should be located nearby or tactile sensor. This is to reduce cable length, where it will reduce electric noise. Second, controller should form a network. Third, controller should be small. Fourth, the controller should output abstract compressed features. Lastly, the sampling period should be synchronous. Five places tactile sensors are installed such as the chest, the right and the left of the upper arms and forearms as shown in Fig. 3.

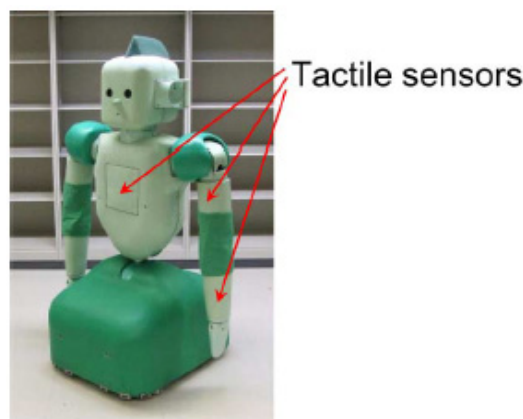


Fig. 3. Tactile sensors in RI-MAN.

In the next paper [5], to detect the hardness of contacted objects, the authors' group proposed to integrate an actuator mechanism onto the tactile sensor. Due to high space and time resolutions, tactile sensors been applied by embedding them into clothes and daily commercial products. Unfortunately it is difficult to be used due to the brittleness of the material. As an alternative, researchers start to use resin materials to fabricate flexible type of sensor structures. A knitted structure was proposed by Konishi et al. and N. Chen et al. [5].

In previous research, the implementation of a tactile sensing function on a fabric structure has been proposed by the Kita et. al. [5] by proposing an artificial hollow fibre as an MEMS material. Through their studies, they investigate the effect on fabric tactile sensor by applying a hand loom, and observe the characteristic of contacted object detection. Fig. 4 shows the schematic view of the fabric tactile sensor. Fig. 4(a) illustrates an artificial hollow fibre. The changes in capacitance between the warp and weft fibres occurred due to load applied at intersection points. It will also cause deformation, as shown in Fig. 4(b).

Lastly [7], in previous proposed devices, some drawback were detected although they able to give a reliable result. Shikida et al. [8], report on an active tactile sensor able to detect both contact force and the hardness of an object. However, precise pneumatic drive and control of a matrix of these sensors could be a formidable task. Helmes et al. [9] and Lindahl et al. [10] used another approach to detect the

physical properties, stiffness, and elasticity of tissue, utilizes a piezoelectric sensor oscillated at resonance frequency. The bimorph could be favored in robotic guided applications in conjunction with a force-torque sensor, but it cannot be used by a human neurosurgeon. Therefore, Claudia [7] proposes a prototype of a multifunctional tactile sensor based on ionic polymer metal composites (IPMCs) as an alternative solution. If mechanical deformation occurred, a low voltage will be generated across their thickness and causes the IPMCs bend.

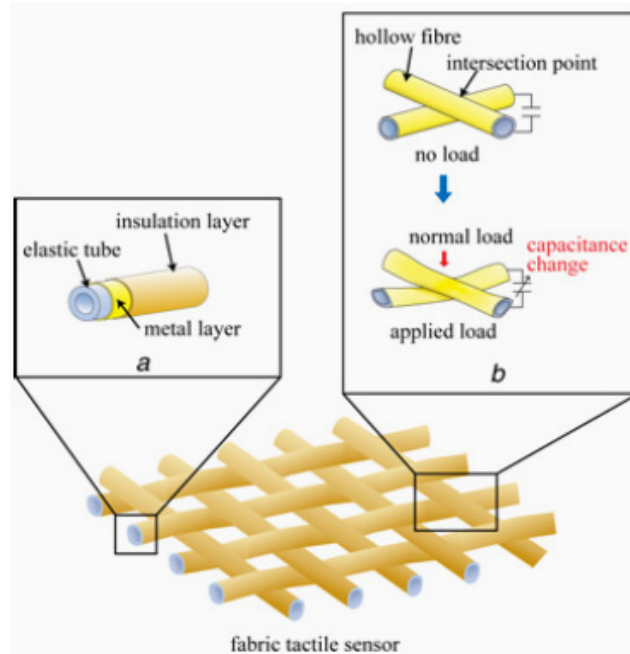


Fig. 4. Schematic view and operation principle of a fabric tactile sensor: (a) Artificial hollow fibre, (b) Operation principle.

4. Result Outcomes and Contribution

Tactile sensor that has been in fabrication has thickness of about 20 μm . From the tests carried out, for the larger size of the membrane, it shows a large deflection for the same load applied. From these tests, the readings for both capacitive sensing began to saturate with a load greater than 0.06 N due to closure of the air gap. It is advisable for every membrane force more than 0.04 N should not be applied. This is to maintain the linear response between capacitive readout and the applied load.

The responses off the pressure sensing element were measured. It shows that the time response has a smooth sinusoidal shape; also the sensor output is almost linear with the applied force. The frequency response of the sensor also was measured. It shows that the system is ideal to about 100 Hz. In the third experiment, the effectiveness of the proposed structure was evaluated. Three difference conditions were tested. The results show the proposed structure has the highest sensitivity.

Other test was to measure the output when weights 1 – 8 kg with an area of 25 mm \times 25 mm were placed on the tactile sensor. Results show the tactile sensor has a satisfactorily measurement resolution. The tactile sensor are placed in five areas, the chest, and the right and left of the upper arm and fore arm. In demonstration on the RI-MAN, a 16 kg dummy human are lift up. In Fig. 5, the realized roll angle and the load detected by the tactile sensors are shown. This shows the tactile sensors succeeded in the detecting changes in the load.

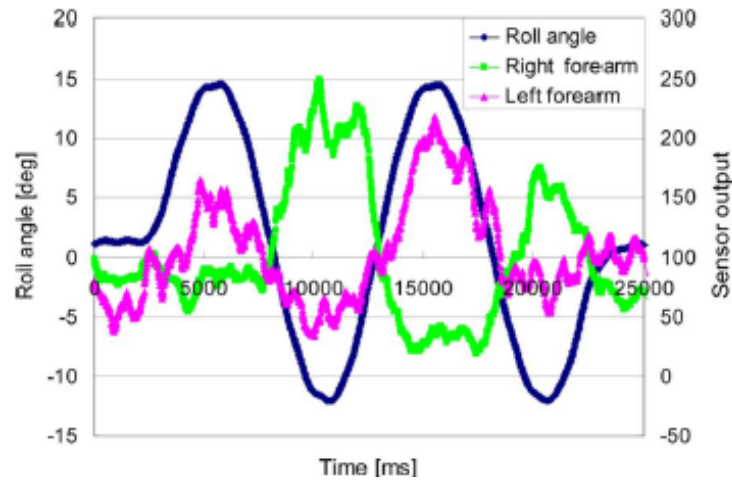


Fig. 5. Cross Roll angle and the load detected by tactile sensors.

Two kinds of fabric tactile sensors having different sizes 87.5×52.0 mm and 180.0×56.0 mm were produced by applying the handloom. The pitch values of the detection point at the horizontal and vertical directions were 7.0 and 7.0 mm, respectively, in the former sensor, and they were 18.0 and 14.0 mm, in the latter one. The developed fabric sensor successfully detected the 2D shape of the contacted objects. It can be referred in Fig. 6.

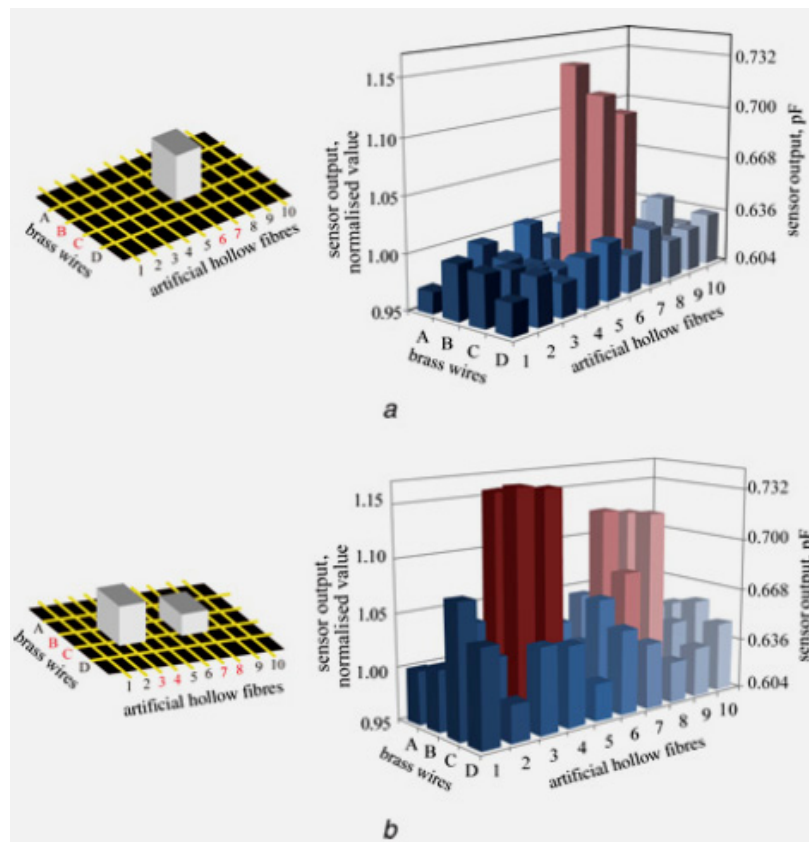


Fig. 6. Detection of the applied distributed force and the object shape:
 (a) Square plate (size: 20×20 mm, force: 2925 mN), (b) Two different weight of square block
 (left: 269 g, right: 187 g, size: 24.2×24.2 mm).

The variation of the signals among the detecting points was less than 1.5 % when the concentrated force was applied to the each sensing point. The sensor output increased with increasing applied load, and it depended on the size of the contacted area. Refer to Fig. 7. The sensor output was the same when the applied pressure on the fabric was the same, even if the contacted areas were different. Refer to Fig. 8.

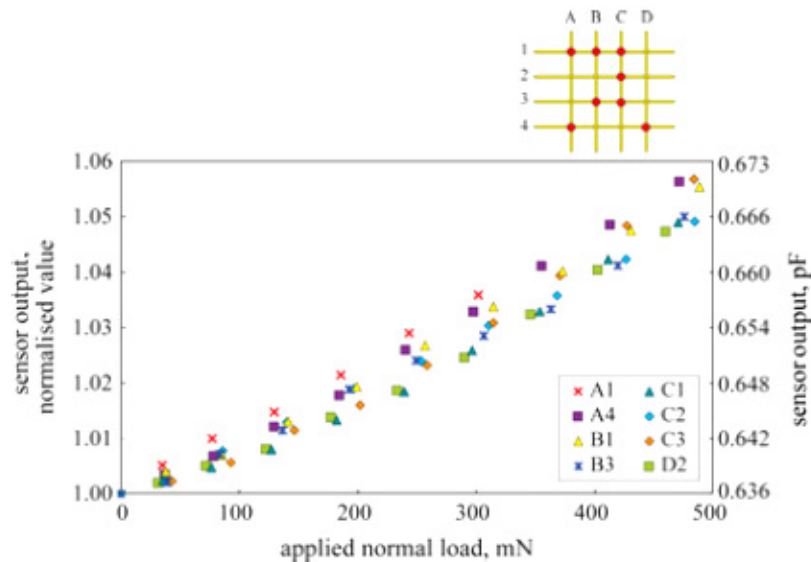


Fig. 7. Relationship between the applied loads and the sensor output at various detecting points (concentrated load was applied to the sensor).

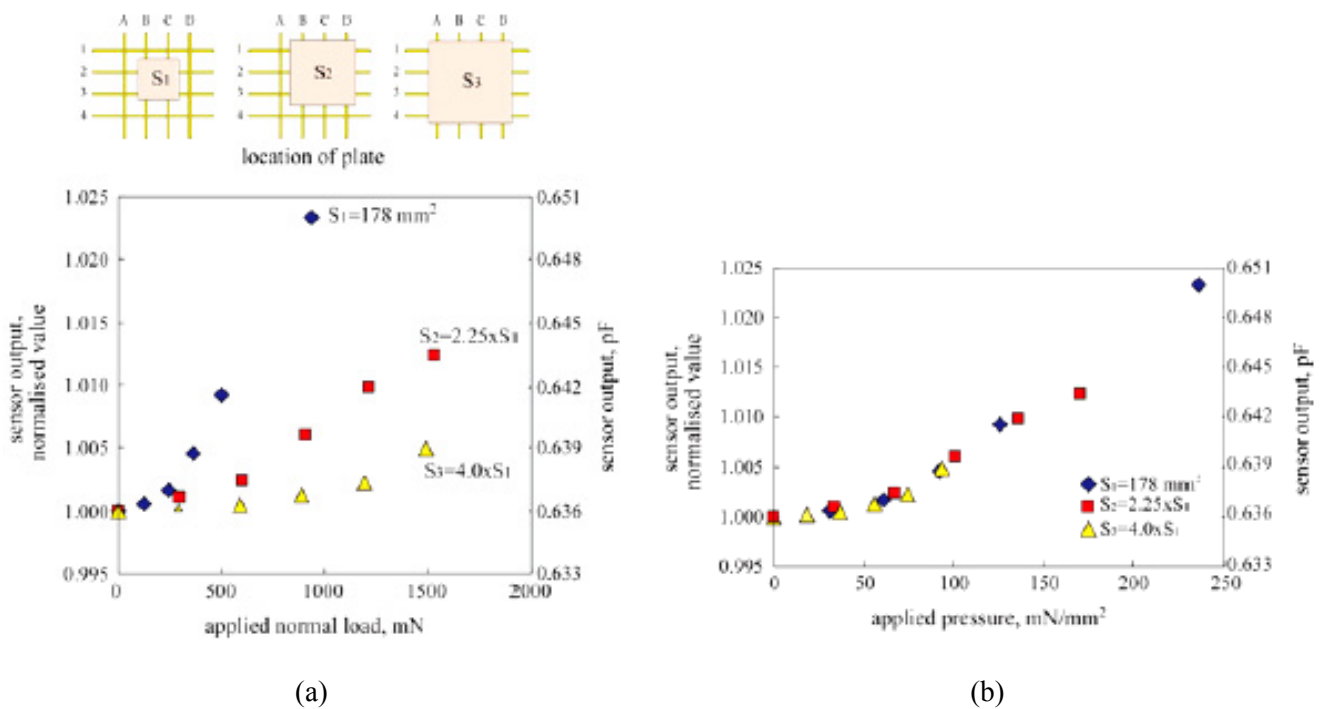


Fig. 8. Characteristics of the contacted object detections under the condition of three different contacted areas at the sensing point of C2: (a) Relationship between the applied load and the sensor output detected, (b) Relationship between the applied pressure and the sensor output detected.

Fig. 9 shows the results relating to testing the on-off mode, where both the actuator input voltage and the sensor output voltage are plotted while the system is moved inside the tube with the window, using a variable-speed motor drive at a constant speed. From the figure it is possible to recognize two different responses by the sensor that corresponds to passing through the closed tube and the window respectively: an alternate signal is obtained when the sensing element is passing through the window while an almost zero signal refers to the passage inside the tube.

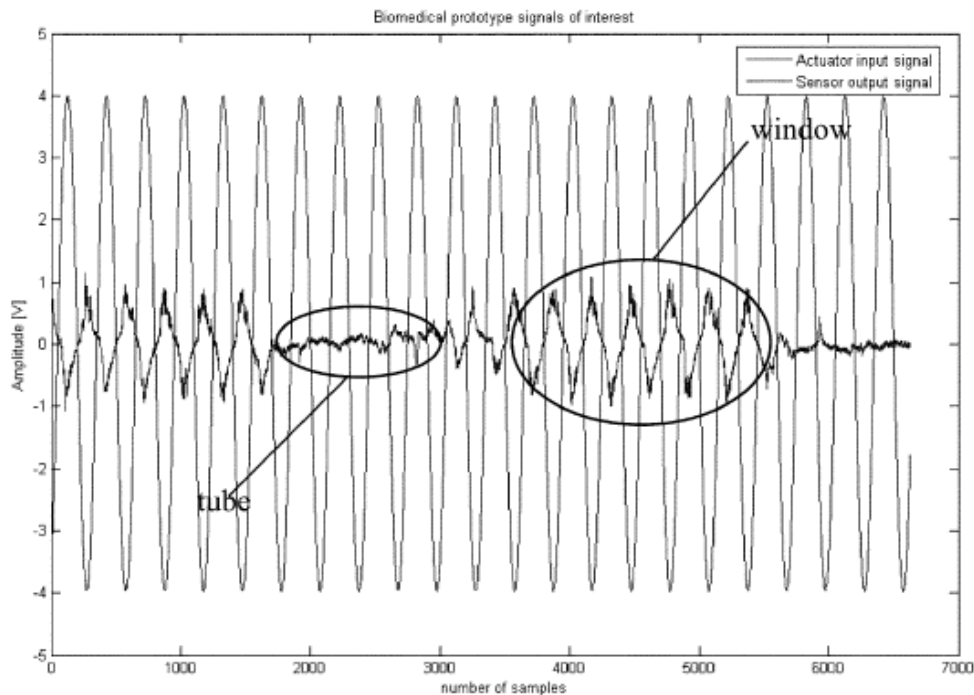


Fig. 9. Actuator input signal and the sensor output signal.

From Figs. 10 and 11, it can be noticed that the sensor output signal is affected by noise. However, the noise does not affect the information required, which is only the amplitude of the sensor output signal.

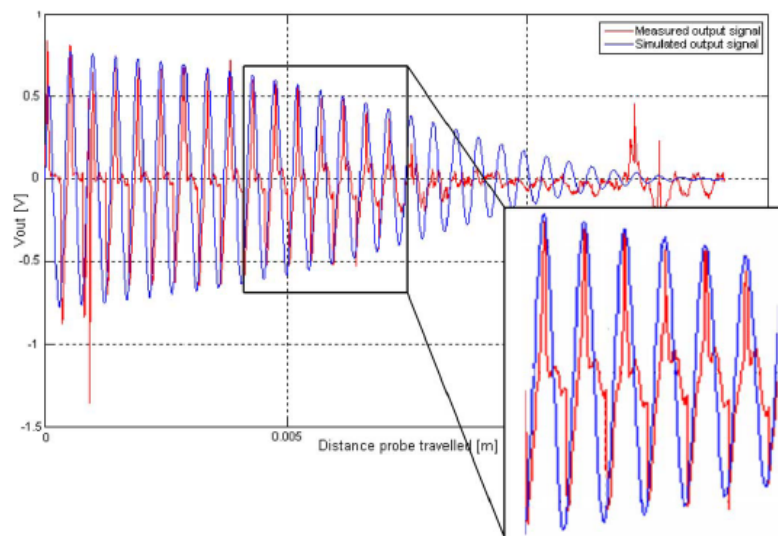


Fig. 10. Sensor output signal while the probe is moved through the window in the tube under the cantilever target.

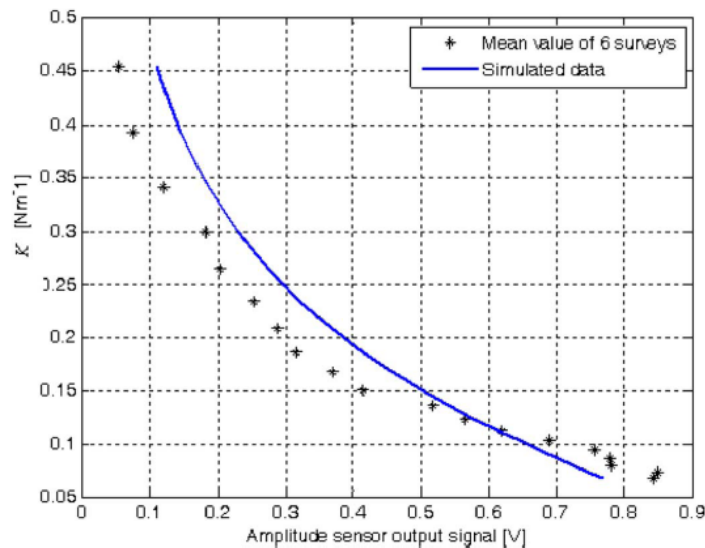


Fig. 11. K versus the maximum amplitude of the sensor output signal at a temperature $t = 25\text{ }^{\circ}\text{C}$ and humidity $h = 35\%$. The dotted line refers to the mean value of 6 different surveys, while the solid line refers to simulated data.

Fig. 11 shows the characteristic curve of K versus the sensor output signal, where the mean value of six different surveys is plotted. The curve obtained shows that each value of the sensor output corresponds to a different elastic constant value.

5. Discussion

The proposed sensor has been successfully fabricated by utilizing five-layer PDMS structure. Due to its size, the sensor can be mounted on any medical instruments. The tactile sensor can detect changes as small as 0.01 MPa on polymer specimen ranging from 0.1 to 0.5 MPa.

Tactile sensor systems for the RI-MAN successfully build. RI-MAN able to detect the magnitude and position of the load based on the experiment performed. There is still some space for improvement in future research. First are to improve the measurement resolution and noise tolerance. Second, is improved the controller and third is to optimize the tactile sensor features so that it will be able detect human tactile sensation such as stroking and hitting.

Regarding on the experiment that have been done in order to investigate the characteristic of the contacted object detection, the authors enlarged the size of the fabric tactile sensor by applying a handloom. Trough the experiment conducted, the fabric tactile sensor able to detect the load by measuring the capacitance changes. Four advantages can be concluded for the fabric tactile sensor:

1. Tactile sensing on arbitrary surface.
2. Tactile sensing of large surface area.
3. Wearable sensors.
4. Detection of two-dimensional (2D) contact force distribution.

A prototype of biomedical application has been developed which exploit the reversibility of the IPMC conversion property. The advantages of using IPMCs are lightweight, low-power consumption, softness, low-cost, and biocompatibility. By recognizing the tissues coming into contact, the device able to recognize and give information on their stiffness. Besides of its simple structure, the device is easy to be operating.

6. Conclusion

Developments and applications in tactile sensor trends over the last five years have been analyzed. Based on the tactile technology, it's not limit to certain application only but it has been growth with variety of application especially in medical [3, 12-14], robotics [4], object recognition [5, 6] and bio-medical [7-10] fields.

Acknowledgements

The authors would like to thank Universiti Teknologi Malaysia (UTM) for all the supports given.

References

- [1]. M. I. Tiwana, S. J. Redmond, N. H. Lovell, A Review of Tactile Sensing Technologies with Applications in Biomedical Engineering, *Sensors & Actuators: A. Physical*, Vol. 179, 2012, p. 17-31.
- [2]. M. Lee, Tactile sensing: new directions, new challenges, *The International Journal of Robotics Research*, 19, 7, 2000, pp. 636.
- [3]. P. Peng, Flexible tactile sensor for tissue elasticity measurements, *Journal of Microelectromechanical Systems*, Vol. 18, 2009, pp. 1226 - 1233.
- [4]. T. Mukai, M. Onishi, T. Odashima, S. Hirano, and Z. Luo, Development of the tactile sensor system of a human-interactive robot "RI-MAN", *IEEE Transactions on Robotics*, Vol. 24, No. 2, April 2008, pp. 505-512.
- [5]. G. Kita, M. Shikida, Y. Suzuki, Y. Tsuji, and K. Sato, Large-sized fabric tactile sensor for detecting contacted object, *Micro & Nano Letters*, 5, 6, 2010, pp. 389-392.
- [6]. Chorley, C., Melhuish, C., Pipe, T., Rossiter, J., Development of a Tactile Sensor Based on Biologically Inspired Edge Encoding, in *Proc. of the International Conference of Advanced Robotics (ICAR' 2009)*, 22-26 June, 2009.
- [7]. C. Bonomo, P. Brunetto, L. Fortuna et al., A tactile sensor for biomedical applications based on IPMCs, *IEEE Sensors Journal*, Vol. 8, No. 8, 2008, pp. 1486.
- [8]. M. Shikida, T. Shimizu, K. Sato, and K. Itoigawa, Active tactile sensor for detecting contact force and hardness of an object, *Sens. Actuators*, Vol. 103, 2003, pp. 213-218.
- [9]. T. Hemsell, R. Stroop, D. O. Uribe, and J. Wallaschek, Resonant vibrating sensors for tactile tissue differentiation, *J. Sound Vibr.*, Vol. 308, 2007, pp. 441-446.
- [10]. O. A. Lindahl, S. Omata, and K. A. Angquist, A tactile sensor for detection of physical properties of human skin in vivo, *J. Med. Eng. Technol.*, Vol. 22, 1998, pp. 147-153.
- [11]. D. Skoog, D. West, Principles of instrumental analysis, Vol. 4, *Saunders College Publishing*, New York, 1985.
- [12]. S. Sokhanvar, M. Packirisamy, and J. Dargahi, MEMS endoscopic tactile sensor: Toward in-situ and in-vivo tissue softness characterization, *IEEE Sensors J.*, Vol. 9, No. 12, 2009, pp. 1679-1687.
- [13]. Kalantari M., Ramezanifard M., Ahmadi R., Dargahi J, Kövecses J., A Piezoresistive Tactile Sensor for Tissue Characterization During Catheter-Based Cardiac Surgery, *Int J. Med Robotics, Comput. Assist. Surg.*, 7, 2011, pp. 431-440.
- [14]. Ahmadi R., Packirisamy M., Dargahi J. and Cecere R., Discretely Loaded Beam-Type Optical Fiber Tactile Sensor for Tissue Manipulation and Palpation in Minimally Invasive Robotic Surgery, *IEEE Sensors J.*, Vol. 12, No. 1, 2012, pp. 22-32.

Guide for Contributors

Aims and Scope

Sensors & Transducers Journal (ISSN 1726-5479) provides an advanced forum for the science and technology of physical, chemical sensors and biosensors. It publishes state-of-the-art reviews, regular research and application specific papers, short notes, letters to Editor and sensors related books reviews as well as academic, practical and commercial information of interest to its readership. Because of it is a peer reviewed international journal, papers rapidly published in *Sensors & Transducers Journal* will receive a very high publicity. The journal is published monthly as twelve issues per year by International Frequency Sensor Association (IFSA). In addition, some special sponsored and conference issues published annually. *Sensors & Transducers Journal* is indexed and abstracted very quickly by Chemical Abstracts, IndexCopernicus Journals Master List, Open J-Gate, Google Scholar, etc. Since 2011 the journal is covered and indexed (including a Scopus, Embase, Engineering Village and Reaxys) in Elsevier products.

Topics Covered

Contributions are invited on all aspects of research, development and application of the science and technology of sensors, transducers and sensor instrumentations. Topics include, but are not restricted to:

- Physical, chemical and biosensors;
- Digital, frequency, period, duty-cycle, time interval, PWM, pulse number output sensors and transducers;
- Theory, principles, effects, design, standardization and modeling;
- Smart sensors and systems;
- Sensor instrumentation;
- Virtual instruments;
- Sensors interfaces, buses and networks;
- Signal processing;
- Frequency (period, duty-cycle)-to-digital converters, ADC;
- Technologies and materials;
- Nanosensors;
- Microsystems;
- Applications.

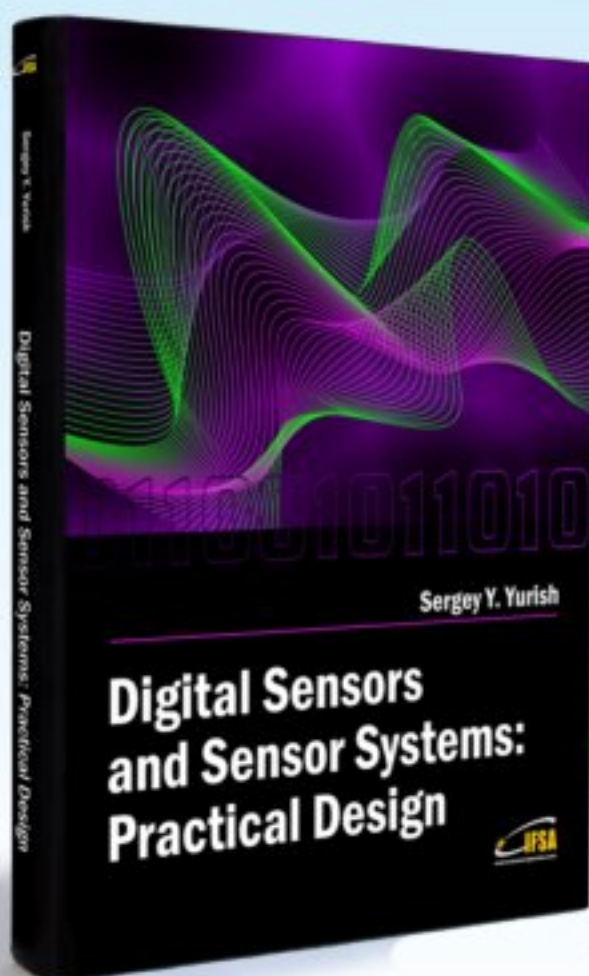
Submission of papers

Articles should be written in English. Authors are invited to submit by e-mail editor@sensorsportal.com 8-14 pages article (including abstract, illustrations (color or grayscale), photos and references) in both: MS Word (doc) and Acrobat (pdf) formats. Detailed preparation instructions, paper example and template of manuscript are available from the journal's webpage: <http://www.sensorsportal.com/HTML/DIGEST/Submission.htm> Authors must follow the instructions strictly when submitting their manuscripts.

Advertising Information

Advertising orders and enquires may be sent to sales@sensorsportal.com Please download also our media kit: http://www.sensorsportal.com/DOWNLOADS/Media_Kit_2012.pdf

Digital Sensors and Sensor Systems: Practical Design will greatly benefit undergraduate and at PhD students, engineers, scientists and researchers in both industry and academia. It is especially suited as a reference guide for practitioners, working for Original Equipment Manufacturers (OEM) electronics market (electronics/hardware), sensor industry, and using commercial-off-the-shelf components, as well as anyone facing new challenges in technologies, and those involved in the design and creation of new digital sensors and sensor systems, including smart and/or intelligent sensors for physical or chemical, electrical or non-electrical quantities.



"It is an outstanding and most completed practical guide about how to deal with frequency, period, duty-cycle, time interval, pulse width modulated, phase-shift and pulse number output sensors and transducers and quickly create various low-cost digital sensors and sensor systems ..." (from a review)

Order online:

http://www.sensorsportal.com/HTML/BOOKSTORE/Digital_Sensors.htm



www.sensorsportal.com